## Kai Zhu

## List of Publications by Year in descending order

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2258059 2272923 4 46 3 4 citations h-index g-index papers 4 4 4 17 all docs docs citations citing authors times ranked

#	Article	IF	CITATIONS
1	Anisotropic growth of electroless nickel‑phosphorus plating on fine sliver lines for L-shape terminal electrode structure of chip inductor. Applied Surface Science, 2019, 496, 143633.	6.1	2
2	Communication—Localized Accelerator Pre-Adsorption to Speed Up Copper Electroplating Microvia Filling. Journal of the Electrochemical Society, 2019, 166, D467-D469.	2.9	3
3	Convection-Dependent Competitive Adsorption between SPS and EO/PO on Copper Surface for Accelerating Trench Filling. Journal of the Electrochemical Society, 2019, 166, D93-D98.	2.9	14
4	Enhancing adhesion performance of sputtering Ti/Cu film on pretreated composite prepreg for stacking structure of IC substrates. Composites Part B: Engineering, 2019, 158, 400-405.	12.0	27